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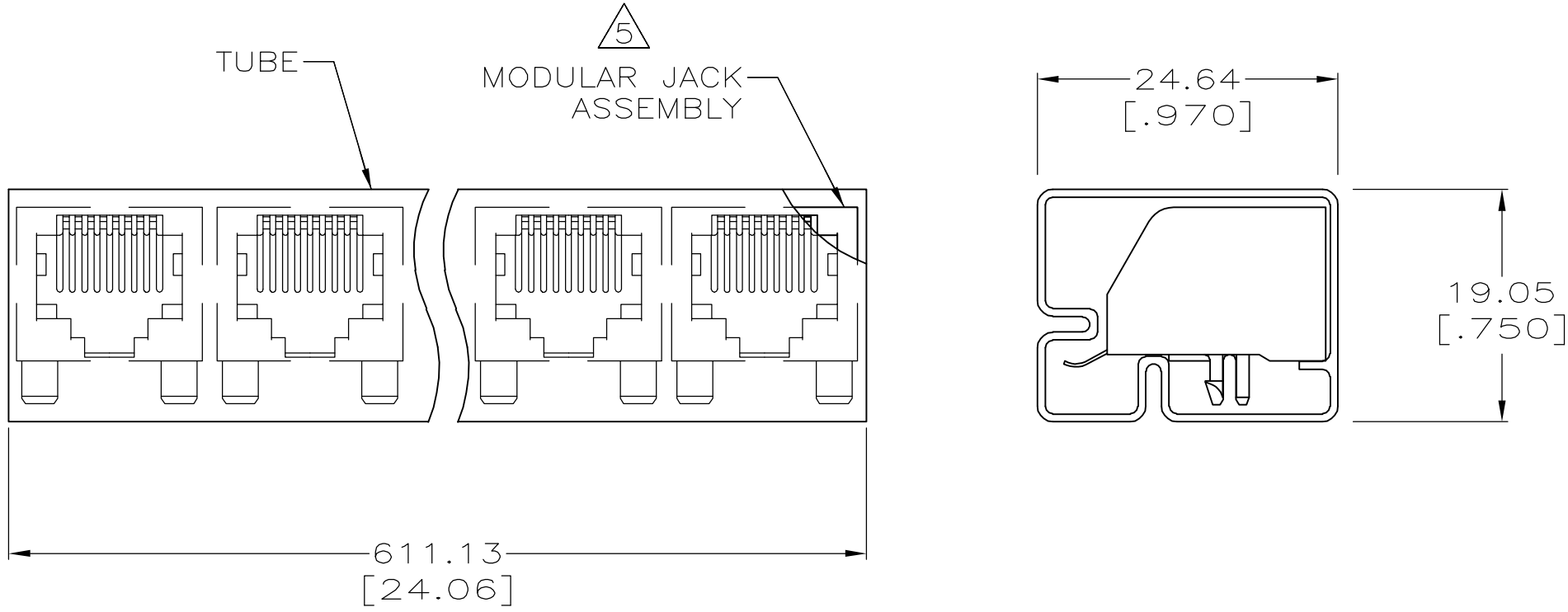
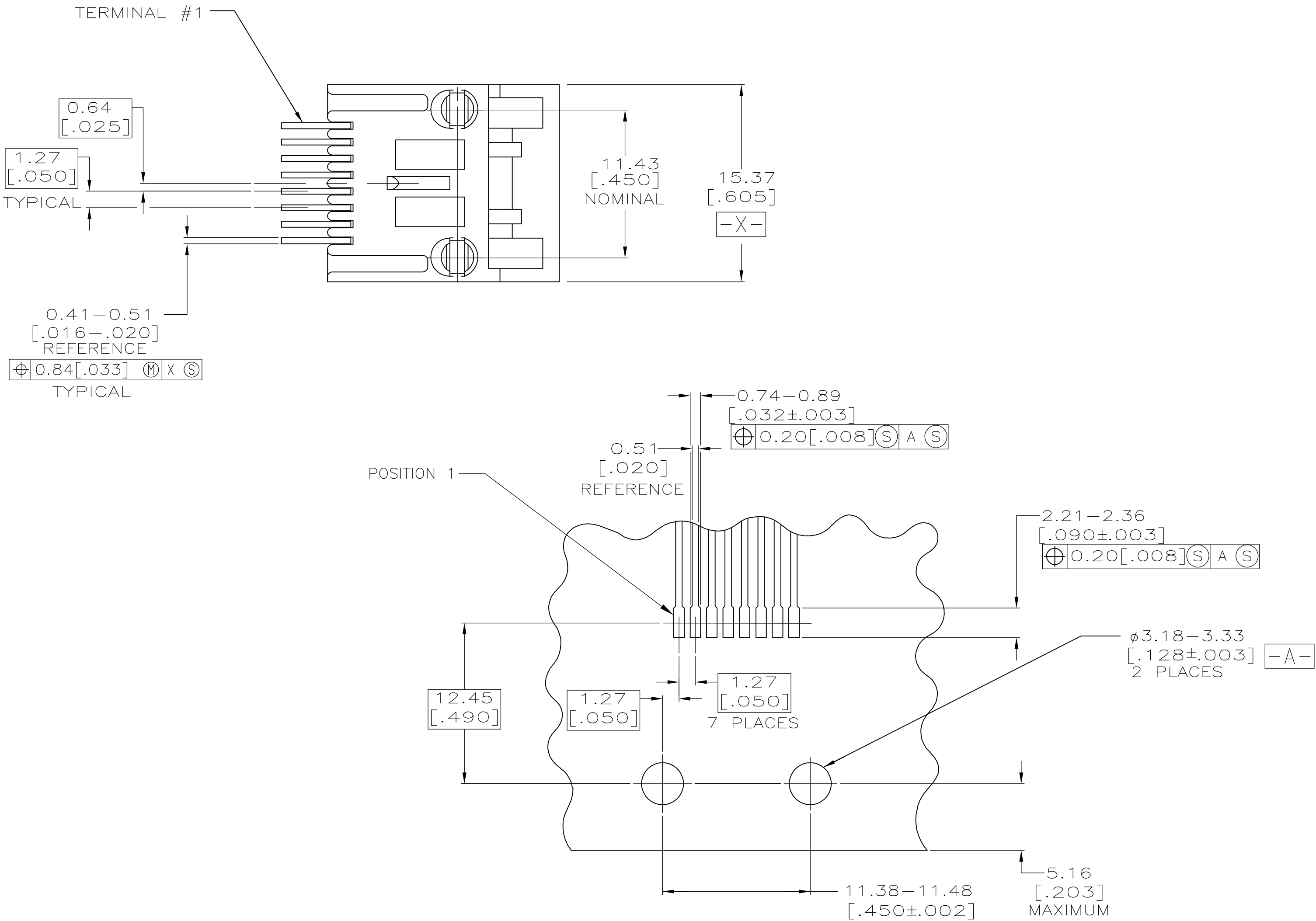
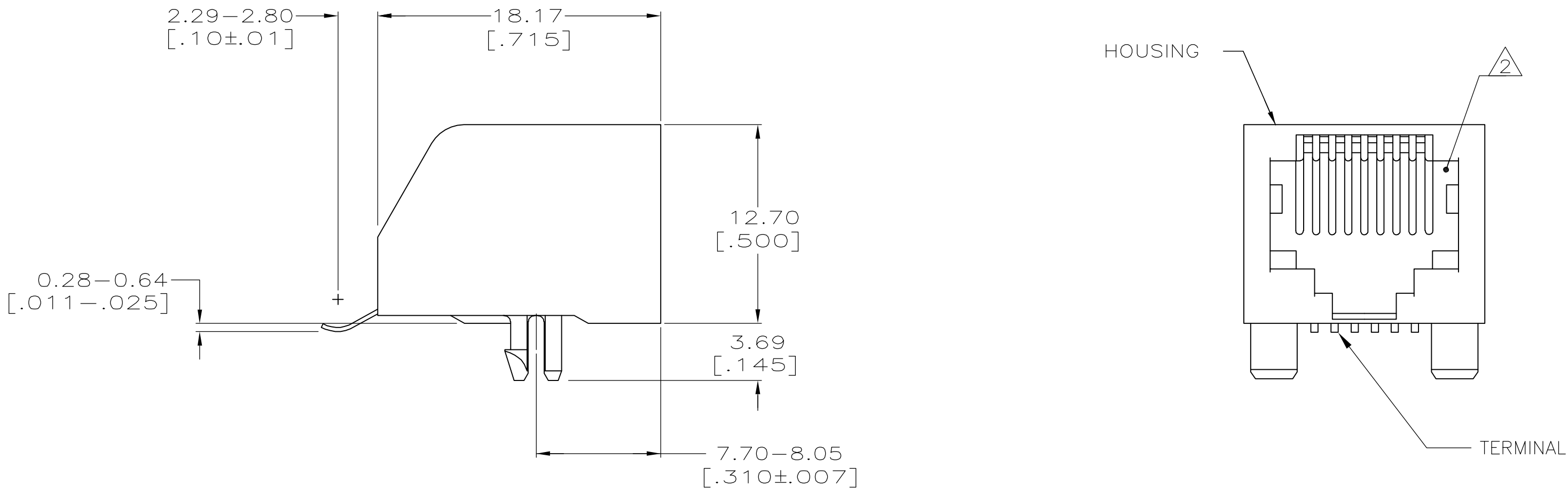
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Jameco Part Number 958489

LOC	DIST	REVISIONS			
AA	22	P	LTR	DESCRIPTION	DATE
		A	REV	PER EC 0511-0201-04	09JUN2005



DETAIL A
SCALE 2:1

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE

- 1 MATERIAL: HOUSING — HTN MOLDING COMPOUND, 94 VO, BLACK.
TERMINAL — 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27 μ m [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μ m [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m [.000050] MINIMUM THICK NICKEL UNDERPLATE.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.
- 5 ASSEMBLIES ARE PACKAGED 36 IN A TUBE.
- 6 ASSEMBLIES ARE BULK PACKAGED.

5	5555764-3
6	5555764-1
PACKAGED	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN G. ATTADIA — DOCK5 09JUN2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm[inches]		CHK J. WESTMAN 09JUN2005	NAME	
		APVD S. FLICKINGER 09JUN2005	PRODUCT SPEC	
			108-1163	
			APPLICATION SPEC	
			114-6040	
MATERIAL			SIZE	RESTRICTED TO
			114-6040	
			WEIGHT	
			-	
			CUSTOMER DRAWING	
			SCALE	1:1
			SHEET	1 OF 1
			REV	A